DAF TAPE ADHERING APPARATUS AND DAF TAPE ADHERING METHOD

ABSTRACT OF THE DISCLOSURE

A method for adhering a DAF tape, and a DAF tape adhering apparatus using the method, are provided. A wafer is secured on a stage in a lower kiln, a DAF tape is held by the lower kiln and an upper kiln arranged to be opposed to the lower kiln, and further, the pressure in the upper kiln is made relatively higher than the pressure in the lower kiln so as to swell the DAF tape and to adhere the DAF tape to the wafer. A table movable toward the DAF tape can be adopted. Further, an air supply part may be provided in the upper kiln. The pressure in the upper kiln may be made higher than the pressure in the lower kiln by supplying air from the air supplying part. A vacuum source connected to the lower kiln may be provided so as to reduce the pressure in the lower kiln. Formation of wrinkles on the DAF tape and trapping of air bubbles under the DAF tape can be prevented.

Figure 1